

ABSTRACT

A semiconductor chip assembly includes a semiconductor chip that includes a conductive pad, a conductive trace that includes a routing line and a pillar, a connection joint that electrically connects the routing line and the pad, and an encapsulant. The
5 routing line extends laterally from the pillar towards the chip, the pillar includes tapered sidewalls, and the chip and the pillar are embedded in the encapsulant and extend vertically beyond the routing line in the same direction.